

Technical Bulletin



Solder plus Support

NC Paste Flux No Clean Flux Gel

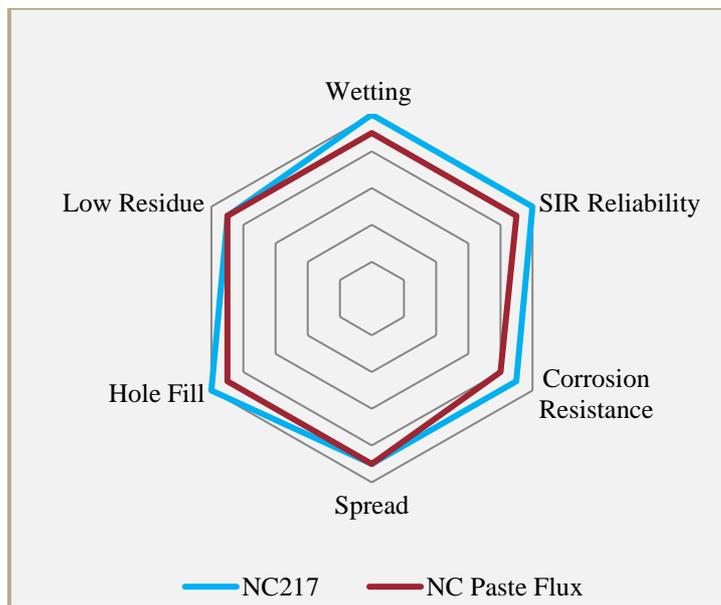
DESCRIPTION

NC Paste Flux is a no clean tacky/rework flux designed for rework, BGA sphere attach and mass transfer processes. NC Paste Flux can be used in all reflow processes from hand soldering to vapor phase reflow. NC Paste Flux residues do not require removal. NC Paste Flux is compatible with all tin-lead and lead-free alloys. NC Paste Flux can be dispensed, stencil printed or hand applied. NC Paste Flux complies with the IPC 7711-7721 standard.

FEATURES AND BENEFITS

- Halogen/Halide-Free
- Low Voiding
- Wide Process Window
- Tin-Lead and Lead-Free Compatible
- Compliant to IPC 7711-7721 Rework/Repair Modification
- High Tack Force for Component Mass Transfer Processes
- ROL0 per IPC J-STD-004

CHARACTERISTICS

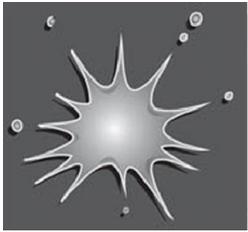


STORAGE & SHELF LIFE

NC Paste Flux has a sealed shelf life of one (1) year when stored 0°C-12°C (32°F-55°F). Do not store near fire or flame. Keep away from sunlight as it may degrade product. NC Paste Flux is shipped ready-to-use, no mixing necessary. Do not mix used and unused chemicals in the same container. Reseal any opened containers. After opening, paste flux shelf life is environment and application dependent.

PARAMETER	TIME	TEMPERATURE
Sealed Refrigerated Shelf Life	1 Year	0°C-12°C (32°F-55°F)
Sealed Unrefrigerated Shelf Life	6 Months	< 25°C (< 77°F)

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APPLICATION

NC Paste Flux is ready to use directly from its container, no thinning required. NC Paste flux is typically dispensed, swabbed or brushed onto the workpiece.

PROCESS GUIDELINES

NC paste flux should be processed according to the alloy and application requirements.

CLEANING

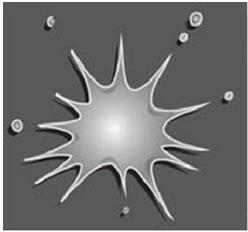
NC Paste Flux can be cleaned using commercially available flux removers. Contact AIM for additional information.

HEALTH & SAFETY

Use with adequate ventilation and proper personal protective equipment. Refer to the accompanying Safety Data Sheet for any specific emergency information. Do not dispose of any hazardous materials in non-approved containers.

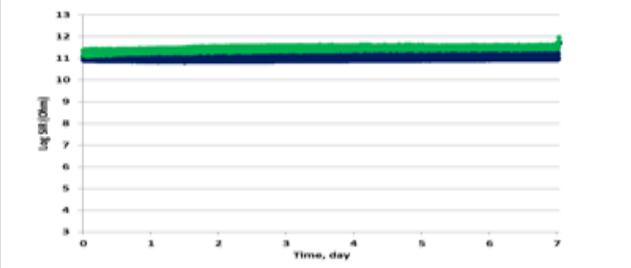
TEST DATA SUMMARY

NAME	TEST METHOD	RESULTS	
IPC Flux Classification	J-STD-004	ROLO	
IPC Flux Classification	J-STD-004B 3.3.1	ROLO	
NAME	TEST METHOD	RESULTS	IMAGE
Copper Mirror	J-STD-004B 3.4.1.1 IPC-TM-650 2.3.32	LOW	
Corrosion	J-STD-004B 3.4.1.2 IPC-TM-650 2.6.15	PASS	
Quantitative Halides	J-STD-004B 3.4.1.3 IPC-TM-650 2.3.28.1	0.0%	
Qualitative Halides, Silver Chromate	J-STD-004B 3.5.1.1 IPC-TM-650 2.3.33	PASS	
Qualitative Halides, Fluoride Spot	J-STD-004B 3.5.1.2 IPC-TM-650 2.3.35.1	No Fluoride	



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NAME	TEST METHOD	RESULTS	IMAGE
Surface Insulation Resistance	J-STD-004B 3.4.1.4 IPC-TM-650 2.6.3.7	All measurements on test patterns exceed 100 MΩ	
Acid Value Determination	J-STD-004B 3.4.2.2 IPC-TM-650 2.3.13	161 ± 3 mgKOH/g flux Typical	
Visual	J-STD-004B 3.4.2.5	PASS	
Wetting	J-STD-005A 3.9 IPC-TM-650 2.4.45	PASS	
Tack	JIS 3284.9	180gf	

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